## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: BAYAN, et al.

Application No.: New

Filed: Herewith

Title: A DIE ATTACH PAD FOR USE IN SEMICONDUCTOR MANUFACTURING AND

METHOD OF MAKING SAME

Attorney Docket No.: NSC1P295/P05886

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on February 26, 2004 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number EV333986859US, addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA

22313-1450.

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Sir:

The undersigned attorney of record in the subject patent application hereby grants an Associate Power of Attorney to Christopher Byrne, Reg. No. 32,204; John Maxin, Reg. No. 34,668; Peter Y. Wang, Reg. No. 40,452; Andrew S. Viger, Reg. No. 28,552; Eugene C. Conser, Reg. No. 39,149; Coleman F. Reif, Reg. No. 38,593; and Allen R. Tremain, Reg. No. 40,207 all of National Semiconductor Corporation to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

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Respectfully submitted,

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Date: February 26, 2004